

Appl. No. 10/605,656  
Amdt. dated March 14, 2005  
Reply to Office action of January 21, 2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

1 (original): A microinjector comprising:

- 5       a chamber for containing fluid;  
          an orifice in fluid communication with the chamber, the orifice disposed above the  
          chamber;  
          an actuator disposed proximately adjacent the orifice and external to the chamber  
          for ejecting fluid from the chamber;  
10       a metal plate disposed above the chamber; and  
          a conduction channel for connecting the metal plate to ground.

- 2 (original): The microinjector of claim 1, wherein the actuator comprises a first actuating  
          component and a second actuating component for sequentially generating a first  
15       bubble and a second bubble respectively.

3 (original): The microinjector of claim 2, wherein the first actuating component has a  
          cross sectional area smaller than that of the second actuating component.

- 20       4 (original): The microinjector of claim 1 further comprising a manifold between a fluid  
          tank and the chamber for passing fluid from the fluid tank to the chamber.

- 5 (original): The microinjector of claim 1 further comprising a driving circuit electrically  
          connected to the actuator for controlling the actuator, an end of the driving circuit  
25       connected to the actuator via a metal connector.

6 (original): The microinjector of claim 5, wherein the metal connector is made of a metal  
          selected from a group consisting of aluminum, gold, copper, tungsten, and alloys of

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Al-Si-Cu.

7 (original): The microinjector of claim 1 further comprising a metal oxide semiconductor  
field effect transistor (MOSFET) electrically connected to the actuator via a metal  
5 connector.

8 (original): The microinjector of claim 1, wherein the conduction channel is made of a  
metal selected from a group consisting of gold and nickel.

10 9 (original): The microinjector of claim 5, wherein the driving circuit comprises  
MOSFETs, bipolar transistors, JFET transistors, or diodes.

10 (new): The microinjector of claim 1, wherein the metal plate is made of a metal  
selected from a group consisting of gold and nickel.

15 11 (new): The microinjector of claim 1 wherein the conduction channel extends through a  
passivation opening for connecting the metal plate to ground.

12 (new): The microinjector of claim 1 further comprising a metal layer disposed between  
20 the chamber and the metal plate.

13 (new): The microinjector of claim 12 wherein the metal layer and the metal plate are  
both connected to ground.

25 14 (new): A method for reducing parasitic capacitance formed in a microinjector structure,  
comprising the steps of:

providing the microinjector, comprising:

a chamber for containing fluid;

an orifice in fluid communication with the chamber, the orifice disposed above

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the chamber;  
an actuator disposed proximately adjacent the orifice and external to the  
chamber for ejecting fluid from the chamber; and  
a metal plate disposed above the chamber; and  
5 forming a conduction channel for connecting the metal plate to ground.

15 (new): The method of claim 14 wherein the conduction channel extends through a  
passivation opening for connecting the metal plate to ground.

10 16 (new): The method of claim 14 further comprising forming a metal layer between the  
chamber and the metal plate.

17 (new): The method of claim 16 wherein the metal layer and the metal plate are both  
connected to ground.

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18 (new): A method of providing shielding protection for a microinjector structure,  
comprising the steps of:  
providing the microinjector, comprising:

a chamber for containing fluid;  
20 an orifice in fluid communication with the chamber, the orifice disposed above  
the chamber;  
an actuator disposed proximately adjacent the orifice and external to the  
chamber for ejecting fluid from the chamber; and  
a metal plate disposed above the chamber; and  
25 forming a conduction channel for connecting the metal plate to ground.

19 (new): The method of claim 18 wherein the conduction channel extends through a  
passivation opening for connecting the metal plate to ground.

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20 (new): The method of claim 18 further comprising forming a metal layer between the chamber and the metal plate.

5 21 (new): The method of claim 20 wherein the metal layer and the metal plate are both connected to ground.